Light is OSRAM



01.08.2015

Dear Customer,

please find attached our OSRAM OS PCN:

OS-PCN-2015-009-A Introduction of UX:3 on 6" Si Carrier and new wire bond for MULTILED Black Surface and TOPLED Black

Important information for your attention:

Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **06.09.2015**.

OSRAM OS aligns with the widely-recognized JEDEC STANDARD "JESD46-B", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change".

Your prompt reply will help OSRAM OS to assure a smooth and well executed transition. If OSRAM OS does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your prompt reply will help OSRAM OS to assure a smooth and well executed transition. If OSRAM OS does not hear from your side by the due date, we will assume your (if you are a Distributor: and your customer's) full acceptance to this proposed change and its implementation.

Your attention and response to this matter is highly appreciated.

Please direct your inquiry to your local Sales office.

OS-PCN-2015-009-A Introduction of UX:3 on 6" Si Carrier and new wire bond for MULTILED Black Surface and TOPLED Black

Subject of change:	A) Introduction of Green UX:3 chip on 6" Si CarrierB) Introduction of reverse bond loopC) Correction of Datasheet Deratings		
Affected products	LRTB GVTG LT TVMG (Change A) only)		
Reason for change:	 A) Secure continuous supply – increase of capacity – growing market demand B) Wire loop improvement – reduced wire bond height C) Datasheet Correction 		
Description of change	Please refer to attached 2_cip_OS-PCN-2015-009-A		
Product identification:	Date code		
Time schedule:	Final qualification report	Available	
	Samples	Available	
	Production release	01.10.2015	
	Start of delivery	15.10.2015 ^{*)} *) or earlier if released by customer	
Assessment	Physical properties remain unchanged. Electro-optical parameters remain unchanged. Chips from 6" wafers are fully miscible with chips from 4" wafers.		
Documentation:	3_cip_OS-PCN-2015-009-A_Chip_qual 4_cip_OS-PCN-2015-009-A_Bond_eval		

Customer approval form OS-PCN-2015-009-A Introduction of UX:3 on 6" Si Carrier and new wire bond for MULTILED Black Surface and TOPLED Black

Please list product(s) affected in your application(s):

Please check the appropriate box below:

• Agreement: We agree with the proposed change and accept start of the shipment upon availability of the new version.

Objections: We have objections:

O Information requested: We need the following information:

Samples requested: We need the following samples:

Sender

Company:

Adress / Location:

Signature:

Date:

Please return this approval form to your Sales partner. OSRAM Opto Semiconductors

GmbH

Head Office:

Leibnizstrasse 4 93055 Regensburg, Germany Phone +49 941 850-5 Fax +49 941 850-1002 www.osram-os.com



Products Affected by Product Change Notification

Number: OS-PCN-2015-009-A

Name: Introduction of UX:3 on 6" Si Carrier and new wire bond for MULTILED Black Surface and TOPLED Black

Release Date: 8/1/2015

Response Due Date: 9/6/2015

Implementation Date: 10/15/2015

Product	QNumber	QNumber Description	Part Number
LRTB GVTG	Q65111A3112	LRTBGVTG-U5V5-1+A5B5-29+S9T9-49-20-	LRTB GVTG-U5V5-1+A5B5-29+S9T9-49
	Q65111A3778	LRTBGVTG-U5V5-1+A5B5-29+S9T9-49-20-	LRTB GVTG-U5V5-1+A5B5-29+S9T9-49-C
	Q65111A3779	LRTBGVTG-U5V5-1+A5A9-26+S9T5-58-20-	LRTB GVTG-U5V5-1+A5A9-26+S9T5-58
	Q65111A5434	LRTBGVTG-U9V5-1+A5A7-57+S9T5-57-20-	LRTB GVTG-U9V5-1+A5A7-57+S9T5-57-C
	Q65111A5435	LRTBGVTG-U9V5-1+A5A7-45+S9T-67-20-F	R LRTB GVTG-U9V5-1+A5A7-45+S9T-67-C
LT TVMG	Q65111A4060	LT TVMG-U1AA-DJ18-0-20-R18	LT TVMG-U1AA-DJ18